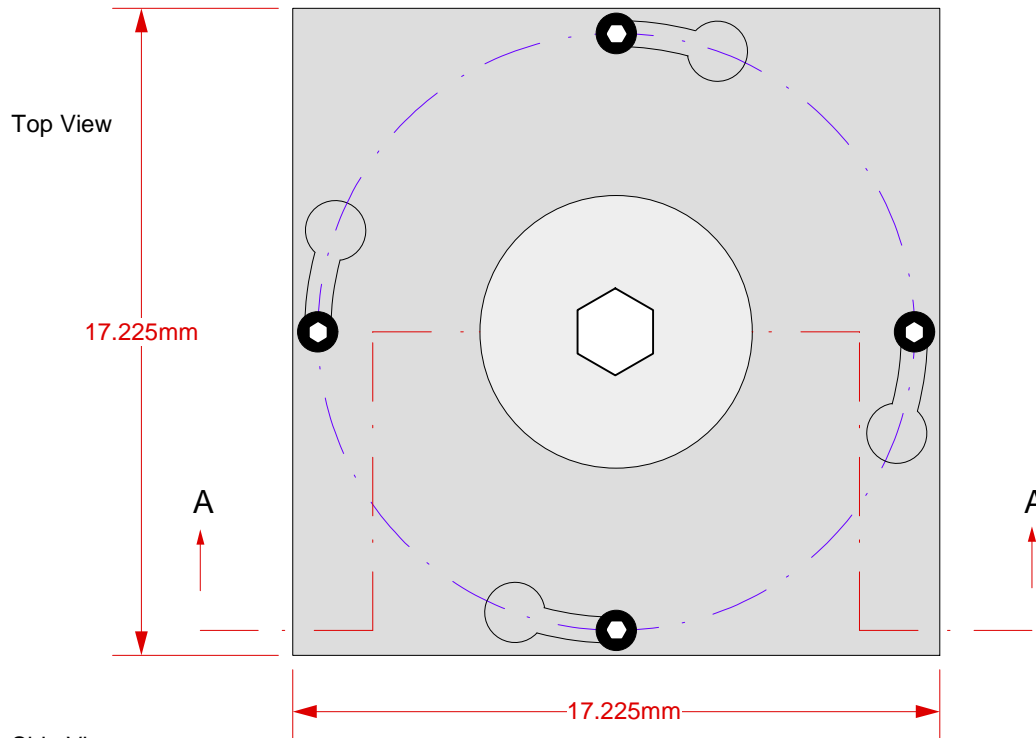
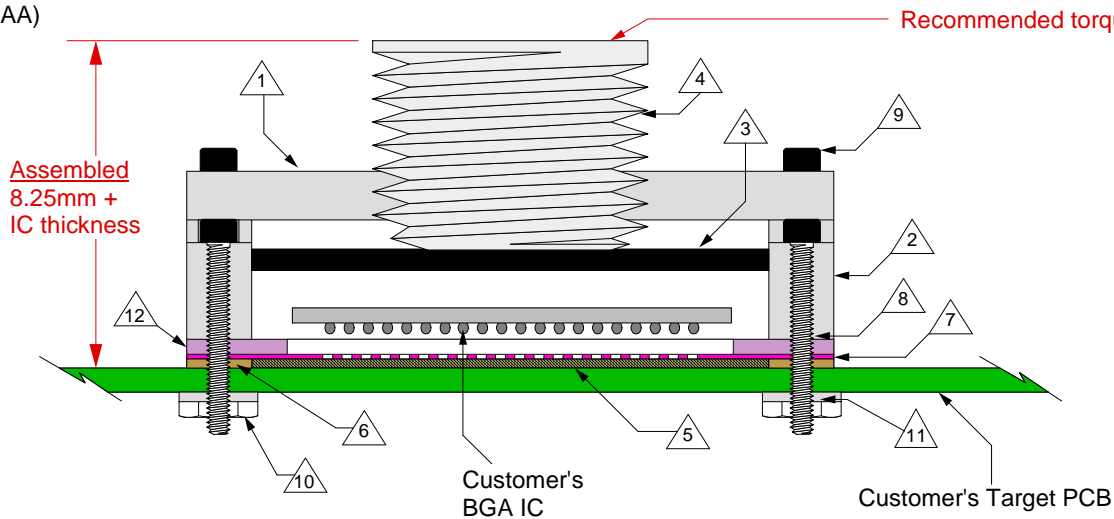


# GHz BGA Socket - Direct mount, solderless



Side View  
(Section AA)



## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Ultem 1000. Thickness = 0.75mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- △ 12 IC guide: FR4

## SG-BGA6108 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337  
Tele: (952) 229-8200  
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: H. Hansen

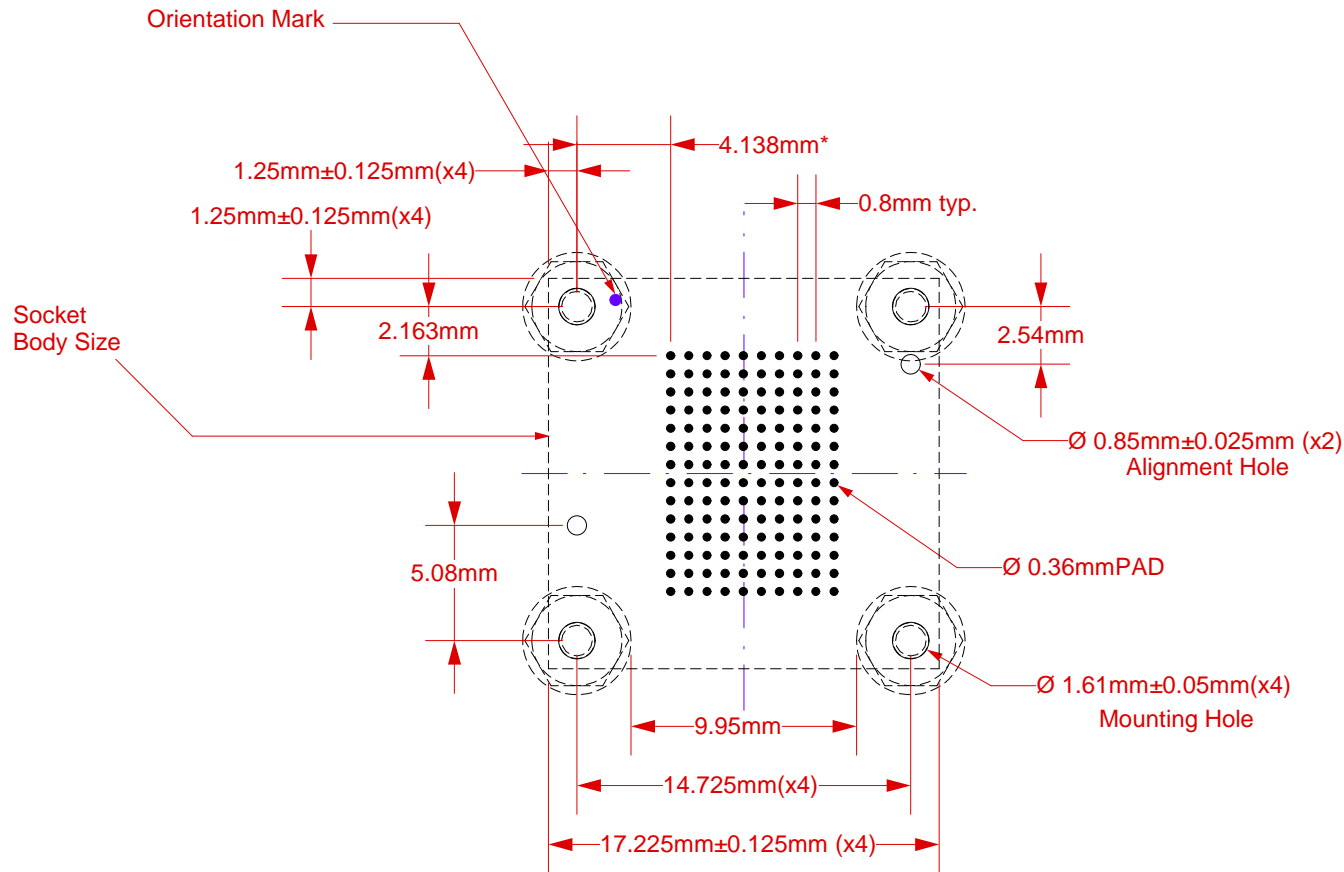
Date: 3/17/04

File: SG-BGA-6108 Dwg.mcd

Modified: 6/12/09, AE

All tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**




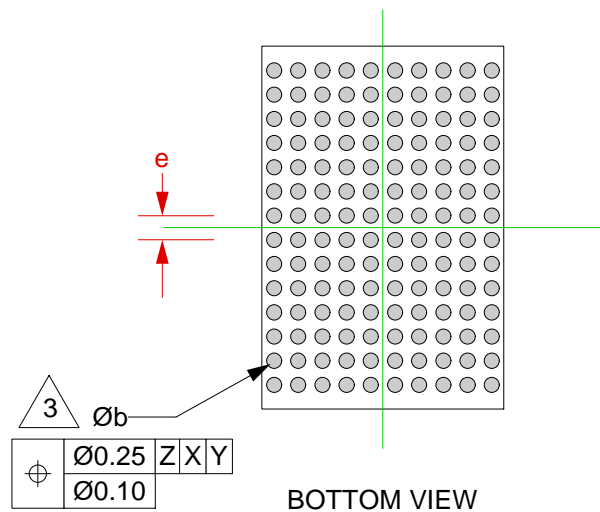
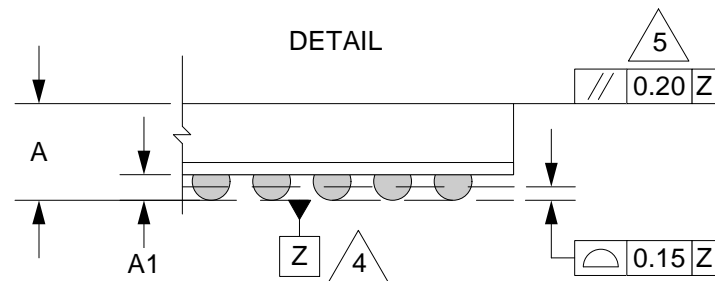
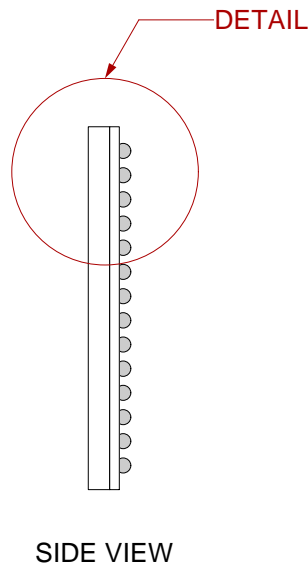
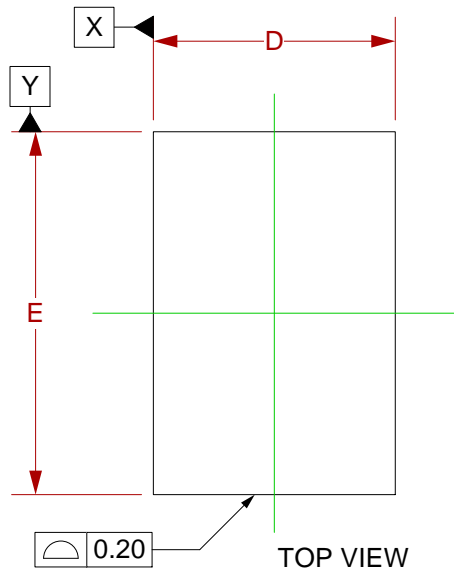
**Target PCB Recommendations**

- Total thickness: 1.6mm min.
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


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	<p>Drawing: H. Hansen</p>	<p>Date: 3/17/04</p>		
	<p>File: SG-BGA-6108 Dwg.mcd</p>	<p>Modified: 6/12/09, AE</p>		



1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.4
A1	0.25	0.35
b		0.50
D	8.00 BSC	
E	12.00 BSC	
e	0.80 BSC	

Array 10x14

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	Drawing: H. Hansen		Date: 3/17/04	
	File: SG-BGA-61089 Dwg		Modified: 6/12/09, AE	